



Toshiba SoC solutions support DS2 in developing low-cost powerline communications chipset for consumer market

SoC process technology, development platform and local engineering support combine to ensure rapid development of low-power 100Mbps chipset

Toshiba Electronics Europe (TEE) has announced a second successful collaboration with DS2, the leading supplier of Universal Powerline Association (UPA) ICs. This time DS2 has used Toshiba's renowned process technology including special developed ADC, DAC and PLL for the rapid development of a next generation, low-cost and low-power 100Mbps powerline communications (PLC) chipset targeted at consumer networking applications.

DS2's 'MONTGO' is an extremely low-cost PLC solution providing a maximum data rate of 100Mbps. Comprising the DSS8101U PHY/MAC SoC and the DSS7800 AFE IC, the chipset is specifically targeted at data networking in consumer applications including products designed for internet sharing, audio distribution and networking in the home. MONTGO offers full interoperability

with DS2's highly successful UPA-DHS (Universal Powerline Association Digital Home Systems Standard) compliant 200Mbps product and future 400Mbps powerline products that deliver the higher performance levels required for video networking.

As with the 200Mbps 'Aitana' announced last year, the new chipset was developed in conjunction with Toshiba's European LSI Design and Engineering Centre (ELDEC) in Düsseldorf. In order to minimise time from initial design concept to volume production, ELDEC engineers used Toshiba's well established implementation platform. In addition, by using Toshiba's advanced process technology and IP libraries, DS2 engineers were able to quickly integrate key on-board features including ADCs, DACs, and PLL functionality.

Dr. Jorge Blasco, the president and CEO of DS2, comments: "The key to the development of the new PLC chipset was to deliver a high quality, advanced and low-power SoC solution in as short a time as possible while ensuring that the price was competitive for consumer applications. Having already supported us in the development of one highly successful 200Mbps PLC implementation we knew that Toshiba had the process technology, development platform and local engineering support that would allow us to meet all of these criteria."

Armin Derpmanns, general manager of the SoC Business Unit at TEE adds: "This is another great example of how Toshiba's combination of technologies, development platforms and support can meet the needs of cutting edge fabless chip makers. Our open and advanced IDM model ensures that companies such as DS2 have access to the technology and development services needed to meet key performance, power, and functionality specifications at the lowest possible cost in the shortest possible time. At the same time, our engineering teams can provide all necessary design implementation, consultancy and project management support."

Mr Tsutsui, senior manager from Toshiba Semiconductor Company, Custom SoC Group in Japan states: "Fabless chip makers are strategic to the growth of Toshiba's SoC business. This latest project shows how we are able to support such companies with every aspect of technology, design and development and on into final production."

More information on Toshiba's ASIC and Foundry technology and services is available at www.toshiba-components.com/ASIC .

About Toshiba

Toshiba Corporation is a leader in information and communications systems, electronic components, consumer products and power systems. The company's integration of these wide-ranging capabilities assures its position as an innovator in advanced components, products and systems. Toshiba has more than 172,000 employees worldwide and annual sales of over US\$54 billion (FY2005).

Toshiba Electronics Europe (TEE) is the European Headquarters for the electronic components business of Toshiba Corporation, which is the world's fourth largest semiconductor vendor according to estimates by Dataquest.

Providing design, manufacturing, marketing and sales, TEE was formed in 1973 in Neuss, Germany. The company now has headquarters in Düsseldorf, Germany and subsidiaries in France, Italy, Spain, Sweden and the United Kingdom. Company president is Mr Shikama and the total number of personnel in Europe is around 400.

Toshiba Electronics Europe offers one of the industry's broadest IC and discrete product lines including high-end memory, microcontrollers, ASICs, ASSPs and display products for automotive, multimedia, consumer, telecoms and networking applications. The company also has a wide range of power semiconductor solutions.

For more company information visit Toshiba's web site at www.toshiba-components.com

About DS2

DS2 is the world's leading supplier of the 200Mbps technology that enables home networking and broadband access over power line, coaxial cable, and telephone wire. DS2 pioneered the industry with the introduction of its 200Mbps chipsets, creating the fastest and highest performance solution for simultaneous data, digital audio and high-definition video transmission. Two pre-eminent industry groups, the Universal Powerline Association (UPA) and the European Union consortium OPERA (Open PLC European Research Alliance) have adopted DS2 technology in support of multi-vendor standard certified product. For more information, please visit www.ds2.es

Contact details for publication:

Toshiba Electronics Europe, Hansaallee 181, D-40549 Düsseldorf, Germany

Tel: +49 (0) 211 5296 0 Fax: +49 (0) 211 5296 792197

Web: <http://www.toshiba-components.com/pressoffice/index.asp>

E-mail: info@toshiba-components.com

Contact details for editorial enquiries:

Silke Daniels, Toshiba Electronics Europe

Tel: +49 (0) 211 5296 197

E-mail: sdaniels@tee.toshiba.de.

Issued by:

Simon Flatt/Andrew Town, Pinnacle Marketing Communications Ltd, Prosperity House, Dawlish Drive, Pinner, Middlesex, HA5 5LN, UK

Tel: +44 (0) 20 8869 9229/9345 Fax: +44 (0) 20 8868 4373.

Web: www.pinnacle-marketing.com

E-mail: simon@pinnaclemarcom.com or andrew@pinnaclemarcom.com

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